

EAST

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	"706389"	US-PGPUB	OR	ON	2006/02/01 17:30
S2	3891	boat same (IC or (intergrated near2 circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 16:59
S3	458563	adhesive and heat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/01 11:45
S4	74	S2 and S3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/01 11:46
S5	6	Melvin near2 Alviar	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/01 11:46
S6	1021	156/322	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/01 14:34
S7	13	S6 and (IC or (intergrated near2 circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/01 14:15
S8	2	("6077382" "6722412").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/01 14:00
S9	23	S6 and (IC or (integrated near2 circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/01 14:23
S10	4295	boat same (IC or (integrated near2 circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/01 14:16
S11	458563	adhesive and heat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/01 14:16

S12	110	S10 and S11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/01 14:16
S13	3891	boat same (IC or (intergrated near2 circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/01 14:16
S14	74	S13 and S11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/01 14:16
S15	36	S12 not S14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/01 14:16
S16	35	S6 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/01 14:34
S17	75748	(IC or (intergrated near2 circuit)) and (rail or tray or (wafer adj cassette))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/01 15:59
S18	458563	adhesive and heat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/01 15:59
S19	3286	S17 and S18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/01 16:00
S20	310	"156"/\$.ccls. and S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/01 16:00
S21	9	("5549716").URPN.	USPAT	OR	ON	2006/02/01 16:27
S22	7	("5173338" "5547537" "5549716" "6205745" "6291261" "6560857" "6574857").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/01 16:35
S23	3	"268240"	US-PGPUB	OR	ON	2006/02/02 16:59

S24	7	yao-ting near2 huang	US-PGPUB; USPAT	OR	ON	2006/02/01 16:41
S25	2	"756307"	US-PGPUB	OR	ON	2006/02/02 16:35
S26	49	"0045430"	USPAT; EPO; JPO; DERWENT	OR	ON	2006/02/01 18:15
S27	2	"200045430"	USPAT; EPO; JPO; DERWENT	OR	ON	2006/02/01 18:16
S28	49	"0045430"	USPAT; EPO; JPO; DERWENT	OR	ON	2006/02/01 18:17
S29	71406	carrier with substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 10:55
S30	551	S29 same (IC or (intergrated near2 circuit) or semiconductor) and adhesive and heat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 10:56
S31	363	S30 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 11:44
S32	57	S30 and (solder near2 mask)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 13:10
S33	0	"438278"	US-PGPUB	OR	ON	2006/02/02 11:44
S34	71406	carrier with substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 15:09
S35	551	S34 same (IC or (intergrated near2 circuit) or semiconductor) and adhesive and heat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 15:10
S36	242	S35 and mask\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 13:10

S37	14602	(silver near2 (paste or glue or adhesive))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/02/02 14:38
S38	395	S37 same (IC or (intergrated near2 circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 14:39
S39	2514	S37 same temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 14:39
S40	266	S39 and (IC or (intergrated near2 circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 14:34
S41	230	(silver near2 (paste or glue or adhesive)) same (moisture)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/02/02 14:38
S42	58	S41 same temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 15:08
S43	260	carrier with (substrate same (heat\$3 with (moisture or water)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 09:32
S44	13	S43 and (IC or (intergrated near2 circuit) or semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 09:32
S45	1112632	(IC or (intergrated near2 circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 17:03
S46	0	S45 same ((bond\$3 adj line) near3 test\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 17:00

S47	0	S45 same ((bond\$3 adj line) near10 test\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 17:00
S48	7	S45 and ((bond\$3 adj line) near10 measur\$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 17:04
S49	4	S45 and ((bond\$3 adj line) near10 (measurement or measuring or measure))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 17:31
S50	1577128	(IC or (integrated near2 circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 17:03
S51	11	S50 and ((bond\$3 adj line) near10 measur\$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 17:04
S52	8	S50 and ((bond\$3 adj line) near10 (measurement or measuring or measure))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 17:43
S53	11	S50 and ((bond\$3 adj line) near10 (measurement or measuring or measure or test\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 17:53
S54	185	S50 and ((bond\$3 adj line) near10 thick\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 17:34
S55	1	(S50 and ((bond\$3 adj line) near10 thick\$4)) same (measuring or measurement or measure)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 17:34
S56	7713	S50 and (bond\$3 near10 (measurement or measuring or measure or test\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 17:53

S57	1046	S50 and ((bond\$3 near10 (measurement or measuring or measure or test\$3)) same thick\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/02 17:54
S58	279	S50 and ((bond\$3 near10 (measurement or measuring or measure or test\$3)) with thick\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 09:17
S59	1577128	(IC or (integrated near2 circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 09:17
S60	155	S59 and ((bond\$3 with (measurement or measuring or measure or test\$3)) near10 thick\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 09:17
S61	524	carrier with (substrate same (heat\$3 with (moisture or water or evaporat\$4)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 09:32
S62	26	S61 and (IC or (intergrated near2 circuit) or semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 09:36
S63	7	("5173338" "5547537" "5549716" "6205745" "6291261" "6560857" "6574857").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 09:55
S64	0	S63 and (moisture or water)	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 09:34
S65	489	((pre-heat\$3 or preheat\$3) with (cassette or tray or boat or rail or carrier)) and (IC or (intergrated near2 circuit) or semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 09:37
S66	355	(((pre-heat\$3 or preheat\$3) with (cassette or tray or boat or rail or carrier)) same temperature) and (IC or (intergrated near2 circuit) or semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 09:37
S67	1	S63 and heat\$3	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 09:56

S68	1	S63 and \$3heat\$3	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 09:56
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